

L Number	Hits	Search Text	DB	Time stamp
71	1	("6271588").PN.	USPAT	2002/06/18 09:21
72	1	"5672912".PN.	USPAT	2002/06/18 09:19
73	5	("4710798"   "5172303"   "5239198"   "5281151"   "5521435").PN.	USPAT	2002/06/18 09:19
74	1	("6353267").PN.	USPAT	2002/06/18 09:42
75	4	("5554887"   "5757066"   "5986335"   "6093958").PN.	USPAT	2002/06/18 09:23
76	24	5554887.URPN.	USPAT	2002/06/18 09:24
77	4	("5554887"   "5757066"   "5986335"   "6093958").PN.	USPAT	2002/06/18 09:39
78	2715	257/787.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/18 09:42
79	313	257/787.ccls. and chip and circuit and (flexible or polyimide)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/18 09:53
80	234	(257/787.ccls. and chip and circuit and (flexible or polyimide)) and (@ad<19981028)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/18 10:12
81	268	438/613.ccls. and (@ad<19981028)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/18 09:53
82	113	(438/613.ccls. and (@ad<19981028)) and chip and circuit and (flexible or polyimide)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/18 10:07
83	31272	(csp or (chip adj scale adj package) or wafer) and (polyimide or flexible or polymer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/18 10:10
84	22545	((csp or (chip adj scale adj package) or wafer) and (polyimide or flexible or polymer)) and (@ad<19981028)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/18 10:10
85	30377	wafer and (polyimide or flexible or polymer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/18 10:11
86	6914	wafer with (polyimide or flexible or polymer or (stress with layer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/18 10:12
87	5220	(wafer with (polyimide or flexible or polymer or (stress with layer))) and (@ad<19981028)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/18 10:13
88	1244	((wafer with (polyimide or flexible or polymer or (stress with layer))) and (@ad<19981028)) and (terminal or ball or bump or solder)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/06/18 10:15